



ENGINEERING DEPT.		PRODUCT SPECIFICATION	SPEC.NO.:	SPCF009H
REVISIONS	ECNT120078	For CF07 Series Connector System	PAGE:	1/5

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and inserted on the specified size FPC and FFC

2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment

EIA – 364 Test methods for electrical connectors

J-STD-020 Resistance to soldering Temperature for through hole Mounted Devices SS-00254 Test methods for electronic components ,LEAD-FREE soldering Part

design standards

3. APPLICABLE SERIES NO.: CF07 Series

4. SHAPE, CONSTRUCTION AND DIMENSIONS See attached drawings

5. MATERIALS
See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 0.5 mm $(.020") \sim 2.0$ mm (.079") 6.2 P.C. Board Layout: See attached drawings

7. ACCOMMODATED FPC/FFC THICKNESS

0.3 +0.04/-0.01 mm (.012+.002/-0")

REVIEWED : <u>Eisley</u> APPROVED : <u>Sun</u> VERIFIED : <u>Michelle</u> .





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8. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Rated current and voltage		1A max. 100V AC/DC max.
8.2	Contact resistance	Dry circuit of DC 20 mV max., 100 mA max.	Less than 20 mΩ
8.3	Dielectric strength	When applied AC 500 V 1 minute between adjacent terminal	No change
8.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than $500 \mathrm{M}\Omega$

9. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT	
9.1	Contact retaining force in insulator	Retention speed 25± 3 mm per minute from housing	More than 0.5 Kgf	
9.2	FPC / FFC withdrawal force (Reference data)	Measure force to withdrawal using 0.30 mm thickness FPC / FFC at speed 25± 3 mm per minute	Over 10 circuits: (0. 2 + 0.04 × no. Contacts) Kgf min. Under 10 circuits: (0.04 × no. Contacts)Kfg min.	
9.3	Durability	Connector shall be subjected to 20 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial	

10. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
10.1	Temperature rise	Then carried the rated current	30°C max.
10.2	Vibration	1.5 mm 10-55-10 HZ / minute each 2 hours for X, Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.





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	ITEM	TEST CONDITION	REQUIREMENT
10.3	Solder ability	Tin-Lead Process :	Minimum:
		Soldering time: 5 ± 0.5 second	90% of immersed area
		Soldering pot: 230 ± 5°C	
		Lead-Free Process:	
		Soldering time: 3 ± 0.5 second	
		Soldering pot: 245 ± 5°C	
10.4	Resistance to	Tin-Lead Process:	No damage
	soldering heat	Refer Reflow temperature profile(12.1)	
		Soldering time: 10 second Max.	
		Soldering pot: 230 ± 5 °C	
		Lead-Free Process:	
		Refer Reflow temperature profile(12.2)	
		Soldering time: 20 second Max.	
		Soldering pot: 250~260°C	
10.5	Heat aging	85 ± 2°C , 96 hours	No damage
10.6	Humidity	40 ± 2 °C , 90-95% RH , 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 8-3
10.7	Temperature cycling	One cycle consists of: $(1) -55 ^{+0}_{-3} $ °C , 30 min. (2)Room temp. 10-15 min. (3) $85 ^{+3}_{-0}$ °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial





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	ITEM	TEST CONDITION	REQUIREMENT
10.8	Salt spray	Temperature: 35 ± 3°C Solution: 5 ± 1% Spray time: 48 ± 4 hours	Appearance: No damage Contact resistance: Less than twice of initial
		(Stamping before plated) Spray time: 24 ± 4 hours	Less than twice of initial
		(Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed.	
		The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without	
		plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	

11. AMBIENT TEMPERATURE RANGE: -25 to +85°C

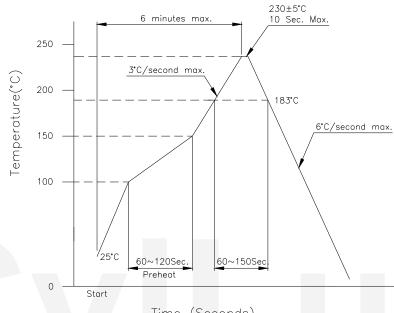




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12. Recommended IR Reflow Temperature Profile:

12.1 Using Typical Solder Paste



Time (Seconds)

12.2 Using Lead-Free Solder Paste

